Tool ID: 305
Tool Location: 107

Equipment Information Sheet

Oxford PECVD

Manager: Jeremy Clark 607-254-6487
Backup: Phil Infante 607-254-4926
Backup: Tom Pennell 607-254-4309
Backup: Philip Schneider 607-254-4931

Calls to staff phones will be automatically forwarded to their cell phones during accessible hours. At other times leave a message or send them an email.

SAFETY

- User must remain in lab while the plasma is on.
- The PECVD can be run at temperatures between 200 C and 400 C.
- The tool uses pyrophoric, toxic and oxidizing gases

USAGE RESTRICTIONS

- User is required to be in the lab during plasma operation.
- For TEOS based SiO2
  - Run "Clean - TEOS", changing the "INNER" and "OUTER" step times each to total deposition time
- For a-Si
  - Run "Clean - aSi", changing the "INNER" and "OUTER" step times each to total deposition time
- For all other materials
  - Run "High Rate Clean" for total deposition time plus 10 minutes.

SCHEDULING/SIGN-UP RESTRICTIONS

Minimum Tool Time: 15 minutes

- 3 Hours Max from 8AM - 5PM
- 12 Hours Total Reservation per 7 days

MATERIALS COMPATIBILITY CATEGORY

Tool Category 5: Class A and B Metals and Compounds

Allowed	Not Allowed
Tool category 1/1E, 2, 3, and 4 materials	
Silicon Based Substrates and Films	
III/V compound Semiconductors	
Glass Substrates	
PECVD and ALD Films	
Cured organics and baked Photoresist	
CNF Class A, B, and Refractory metals	
Exposed Gold, Silver, Copper	
Alkali and Alkaline Compounds	
Organic/Biology Molecules prepared-w/salt buffers	
High Vapor Pressure Materials (Mg, Ca, Zn)*	* Some tool restrictions on high vapor pressure materials may apply
Soft organic materials	

High Vapor Pressure Metals and Compounds are materials that have a vapor pressure above 1e-6 Torr at 400 C.

Additional Material Restrictions and Exceptions

- No general material restrictions

- Resists or other polymers must be cured at 25C above the temperature of the hotplate.
- RF Power is limited to 200W

Last Updated: 04/30/2026